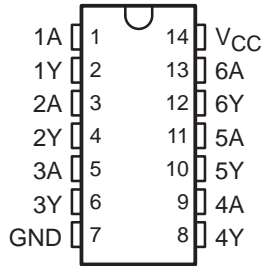


SN54HCU04, SN74HCU04 HEX INVERTERS

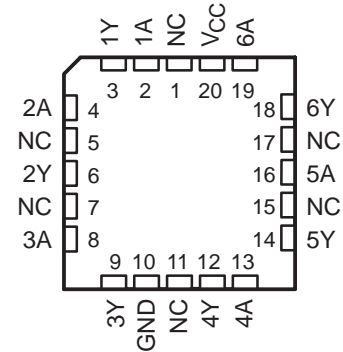
SCLS079E – MARCH 1984 – REVISED MARCH 2004

- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 20- μ A Max I_{CC}
- Typical $t_{pd} = 7$ ns
- ± 4 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Max
- Unbuffered Outputs

SN54HCU04 . . . J OR W PACKAGE
SN74HCU04 . . . D, DB, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54HCU04 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

The 'HCU04 devices contain six independent inverters. They perform the Boolean function $Y = \bar{A}$ in positive logic.

ORDERING INFORMATION

| TA | PACKAGE† | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|------------|--------------|-----------------------|------------------|
| -40°C to 85°C | PDIP – N | Tube of 25 | SN74HCU04N | SN74HCU04N |
| | SOIC – D | Tube of 50 | SN74HCU04D | HCU04 |
| | | Reel of 2500 | SN74HCU04DR | |
| | | Reel of 250 | SN74HCU04DT | |
| | SOP – NS | Reel of 2000 | SN74HCU04NSR | HCU04 |
| | SSOP – DB | Reel of 2000 | SN74HCU04DBR | HU04 |
| | TSSOP – PW | Reel of 90 | SN74HCU04PW | HCU04 |
| Reel of 2000 | | SN74HCU04PWR | | |
| Reel of 250 | | SN74HCU04PWT | | |
| -55°C to 125°C | CDIP – J | Tube of 25 | SNJ54HCU04J | SNJ54HCU04J |
| | CFP – W | Tube of 150 | SNJ54HCU04W | SNJ54HCU04W |
| | LCCC – FK | Tube of 55 | SNJ54HCU04FK | SNJ54HCU04FK |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SN54HCU04, SN74HCU04 HEX INVERTERS

SCLS079E – MARCH 1984 – REVISED MARCH 2004

FUNCTION TABLE
(each inverter)

| INPUT A | OUTPUT Y |
|------------|-------------|
| H | L |
| L | H |

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| | |
|---|----------------|
| Supply voltage range, V_{CC} | -0.5 V to 7 V |
| Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1) | ± 20 mA |
| Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1) | ± 20 mA |
| Continuous output current, I_O ($V_O = 0$ to V_{CC}) | ± 25 mA |
| Continuous current through V_{CC} or GND | ± 50 mA |
| Package thermal impedance, θ_{JA} (see Note 2): | |
| D package | 86°C/W |
| DB package | 96°C/W |
| N package | 80°C/W |
| NS package | 76°C/W |
| PW package | 113°C/W |
| Storage temperature range, T_{stg} | -65°C to 150°C |

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

| | | SN54HCU04 | | | SN74HCU04 | | | UNIT |
|----------|--------------------------------|------------------|-----|----------|-----------|------|----------|------|
| | | MIN | NOM | MAX | MIN | NOM | MAX | |
| V_{CC} | Supply voltage | 2 | 5 | 6 | 2 | 5 | 6 | V |
| V_{IH} | High-level input voltage | $V_{CC} = 2$ V | 1.7 | | 1.7 | | | V |
| | | $V_{CC} = 4.5$ V | 3.6 | | 3.6 | | | |
| | | $V_{CC} = 6$ V | 4.8 | | 4.8 | | | |
| V_{IL} | Low-level input voltage | $V_{CC} = 2$ V | | 0.5 | | 0.5 | | V |
| | | $V_{CC} = 4.5$ V | | 1.35 | | 1.35 | | |
| | | $V_{CC} = 6$ V | | 1.8 | | 1.8 | | |
| V_I | Input voltage | 0 | | V_{CC} | 0 | | V_{CC} | V |
| V_O | Output voltage | 0 | | V_{CC} | 0 | | V_{CC} | V |
| T_A | Operating free-air temperature | -55 | | 125 | -40 | | 85 | °C |

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN54HCU04, SN74HCU04 HEX INVERTERS

SCLS079E – MARCH 1984 – REVISED MARCH 2004

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | | V _{CC} | T _A = 25°C | | | SN54HCU04 | | SN74HCU04 | | UNIT |
|-----------------|---|---------------------------|-----------------|-----------------------|-----|-----|-----------|-----|-----------|-----|------|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| V _{OH} | V _I = V _{CC} or GND | I _{OH} = -20 μA | 2 V | 1.8 | | | 1.8 | | 1.8 | | V |
| | | | 4.5 V | 4 | | | 4 | | 4 | | |
| | | | 6 V | 5.5 | | | 5.5 | | 5.5 | | |
| | | I _{OH} = -4 mA | 4.5 V | 3.98 | | | 3.7 | | 3.84 | | |
| | | I _{OH} = -5.2 mA | 6 V | 5.48 | | | 5.2 | | 5.34 | | |
| V _{OL} | V _I = V _{CC} or GND | I _{OL} = 20 μA | 2 V | | | | 0.2 | | 0.2 | | V |
| | | | 4.5 V | | | | 0.5 | | 0.5 | | |
| | | | 6 V | | | | 0.5 | | 0.5 | | |
| | | I _{OL} = 4 mA | 4.5 V | | | | 0.26 | | 0.4 | | |
| | | I _{OL} = 5.2 mA | 6 V | | | | 0.26 | | 0.4 | | |
| I _I | V _I = V _{CC} or 0 | | 6 V | ±100 | | | ±1000 | | ±1000 | | nA |
| I _{CC} | V _I = V _{CC} or 0, I _O = 0 | | 6 V | 2 | | | 40 | | 20 | | μA |
| C _i | | | 2 V to 6 V | 3 | | | 10 | | 10 | | pF |

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V _{CC} | T _A = 25°C | | | SN54HCU04 | | SN74HCU04 | | UNIT |
|-----------------|--------------|-------------|-----------------|-----------------------|-----|-----|-----------|-----|-----------|-----|------|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| t _{pd} | A | Y | 2 V | 40 | | | 80 | | 120 | | ns |
| | | | 4.5 V | 8 | | | 16 | | 24 | | |
| | | | 6 V | 7 | | | 14 | | 20 | | |
| t _f | | Y | 2 V | 38 | | | 75 | | 110 | | ns |
| | | | 4.5 V | 8 | | | 15 | | 22 | | |
| | | | 6 V | 6 | | | 13 | | 19 | | |

operating characteristics, T_A = 25°C

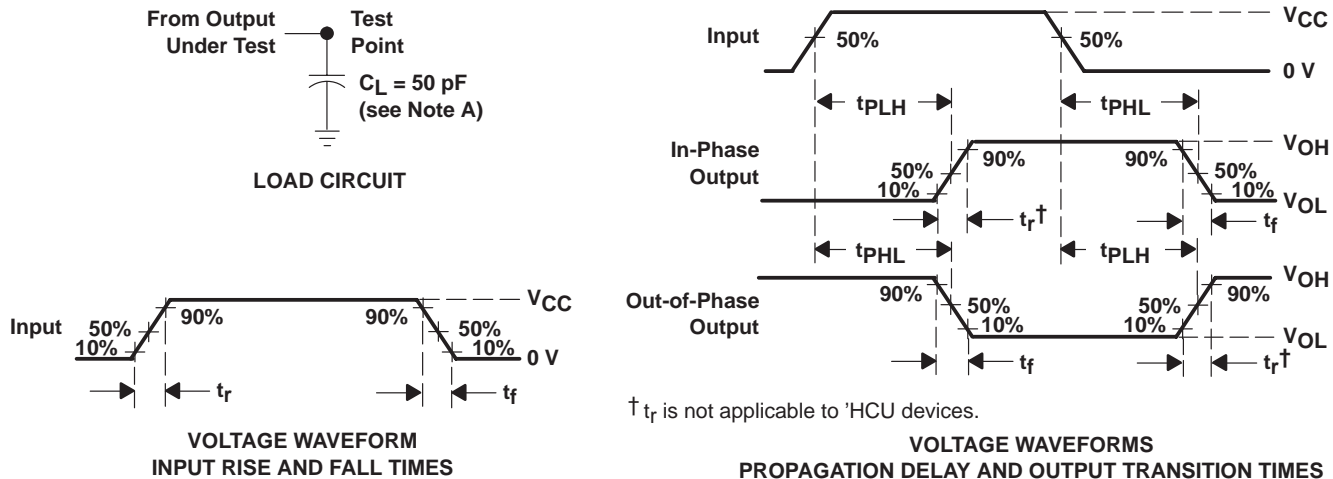
| PARAMETER | TEST CONDITIONS | TYP | UNIT |
|--|-----------------|-----|------|
| C _{pd} Power dissipation capacitance per inverter | No load | 20 | pF |



SN54HCU04, SN74HCU04 HEX INVERTERS

SCLS079E – MARCH 1984 – REVISED MARCH 2004

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and test-fixture capacitance.
 - B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r = 6 \text{ ns}$, $t_f = 6 \text{ ns}$.
 - C. The outputs are measured one at a time, with one input transition per measurement.
 - D. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------------|-------------------------|
| 86010012A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 86010012A SNJ54HCU 04FK | Samples |
| 8601001CA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 8601001CA SNJ54HCU04J | Samples |
| SN54HCU04J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | SN54HCU04J | Samples |
| SN74HCU04D | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HCU04 | Samples |
| SN74HCU04DBRE4 | ACTIVE | SSOP | DB | 14 | | TBD | Call TI | Call TI | -40 to 85 | | Samples |
| SN74HCU04DBRG4 | ACTIVE | SSOP | DB | 14 | | TBD | Call TI | Call TI | -40 to 85 | | Samples |
| SN74HCU04DE4 | ACTIVE | SOIC | D | 14 | | TBD | Call TI | Call TI | -40 to 85 | | Samples |
| SN74HCU04DG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HCU04 | Samples |
| SN74HCU04DR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU CU SN | Level-1-260C-UNLIM | -40 to 85 | HCU04 | Samples |
| SN74HCU04DRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HCU04 | Samples |
| SN74HCU04DRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HCU04 | Samples |
| SN74HCU04DT | ACTIVE | SOIC | D | 14 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HCU04 | Samples |
| SN74HCU04DTE4 | ACTIVE | SOIC | D | 14 | | TBD | Call TI | Call TI | -40 to 85 | | Samples |
| SN74HCU04DTG4 | ACTIVE | SOIC | D | 14 | | TBD | Call TI | Call TI | -40 to 85 | | Samples |
| SN74HCU04N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -40 to 85 | SN74HCU04N | Samples |
| SN74HCU04N3 | OBSOLETE | PDIP | N | 14 | | TBD | Call TI | Call TI | -40 to 85 | | |
| SN74HCU04NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -40 to 85 | SN74HCU04N | Samples |
| SN74HCU04NSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HCU04 | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------------|-------------------------|
| SN74HCU04NSRE4 | ACTIVE | SO | NS | 14 | | TBD | Call TI | Call TI | -40 to 85 | | Samples |
| SN74HCU04NSRG4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HCU04 | Samples |
| SN74HCU04PW | ACTIVE | TSSOP | PW | 14 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HCU04 | Samples |
| SN74HCU04PWE4 | ACTIVE | TSSOP | PW | 14 | | TBD | Call TI | Call TI | -40 to 85 | | Samples |
| SN74HCU04PWG4 | ACTIVE | TSSOP | PW | 14 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HCU04 | Samples |
| SN74HCU04PWR | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU CU SN | Level-1-260C-UNLIM | -40 to 85 | HCU04 | Samples |
| SN74HCU04PWRE4 | ACTIVE | TSSOP | PW | 14 | | TBD | Call TI | Call TI | -40 to 85 | | Samples |
| SN74HCU04PWRG4 | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HCU04 | Samples |
| SN74HCU04PWT | ACTIVE | TSSOP | PW | 14 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HCU04 | Samples |
| SN74HCU04PWTE4 | ACTIVE | TSSOP | PW | 14 | | TBD | Call TI | Call TI | -40 to 85 | | Samples |
| SN74HCU04PWTG4 | ACTIVE | TSSOP | PW | 14 | | TBD | Call TI | Call TI | -40 to 85 | | Samples |
| SNJ54HCU04FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type | -55 to 125 | 86010012A SNJ54HCU 04FK | Samples |
| SNJ54HCU04J | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | 8601001CA SNJ54HCU04J | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54HCU04, SN74HCU04 :

● Catalog: [SN74HCU04](#)

● Military: [SN54HCU04](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

● Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74HCU04DR | SOIC | D | 14 | 2500 | 330.0 | 16.8 | 6.5 | 9.5 | 2.3 | 8.0 | 16.0 | Q1 |
| SN74HCU04DR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74HCU04DR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74HCU04DRG4 | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74HCU04DRG4 | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74HCU04DT | SOIC | D | 14 | 250 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74HCU04PWR | TSSOP | PW | 14 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74HCU04PWT | TSSOP | PW | 14 | 250 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74HCU04DR | SOIC | D | 14 | 2500 | 364.0 | 364.0 | 27.0 |
| SN74HCU04DR | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |
| SN74HCU04DR | SOIC | D | 14 | 2500 | 333.2 | 345.9 | 28.6 |
| SN74HCU04DRG4 | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |
| SN74HCU04DRG4 | SOIC | D | 14 | 2500 | 333.2 | 345.9 | 28.6 |
| SN74HCU04DT | SOIC | D | 14 | 250 | 367.0 | 367.0 | 38.0 |
| SN74HCU04PWR | TSSOP | PW | 14 | 2000 | 367.0 | 367.0 | 35.0 |
| SN74HCU04PWT | TSSOP | PW | 14 | 250 | 367.0 | 367.0 | 35.0 |

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



| NO. OF TERMINALS ** | A | | B | |
|---------------------|------------------|------------------|------------------|------------------|
| | MIN | MAX | MIN | MAX |
| 20 | 0.342 (8,69) | 0.358 (9,09) | 0.307 (7,80) | 0.358 (9,09) |
| 28 | 0.442 (11,23) | 0.458 (11,63) | 0.406 (10,31) | 0.458 (11,63) |
| 44 | 0.640 (16,26) | 0.660 (16,76) | 0.495 (12,58) | 0.560 (14,22) |
| 52 | 0.740 (18,78) | 0.761 (19,32) | 0.495 (12,58) | 0.560 (14,22) |
| 68 | 0.938 (23,83) | 0.962 (24,43) | 0.850 (21,6) | 0.858 (21,8) |
| 84 | 1.141 (28,99) | 1.165 (29,59) | 1.047 (26,6) | 1.063 (27,0) |



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

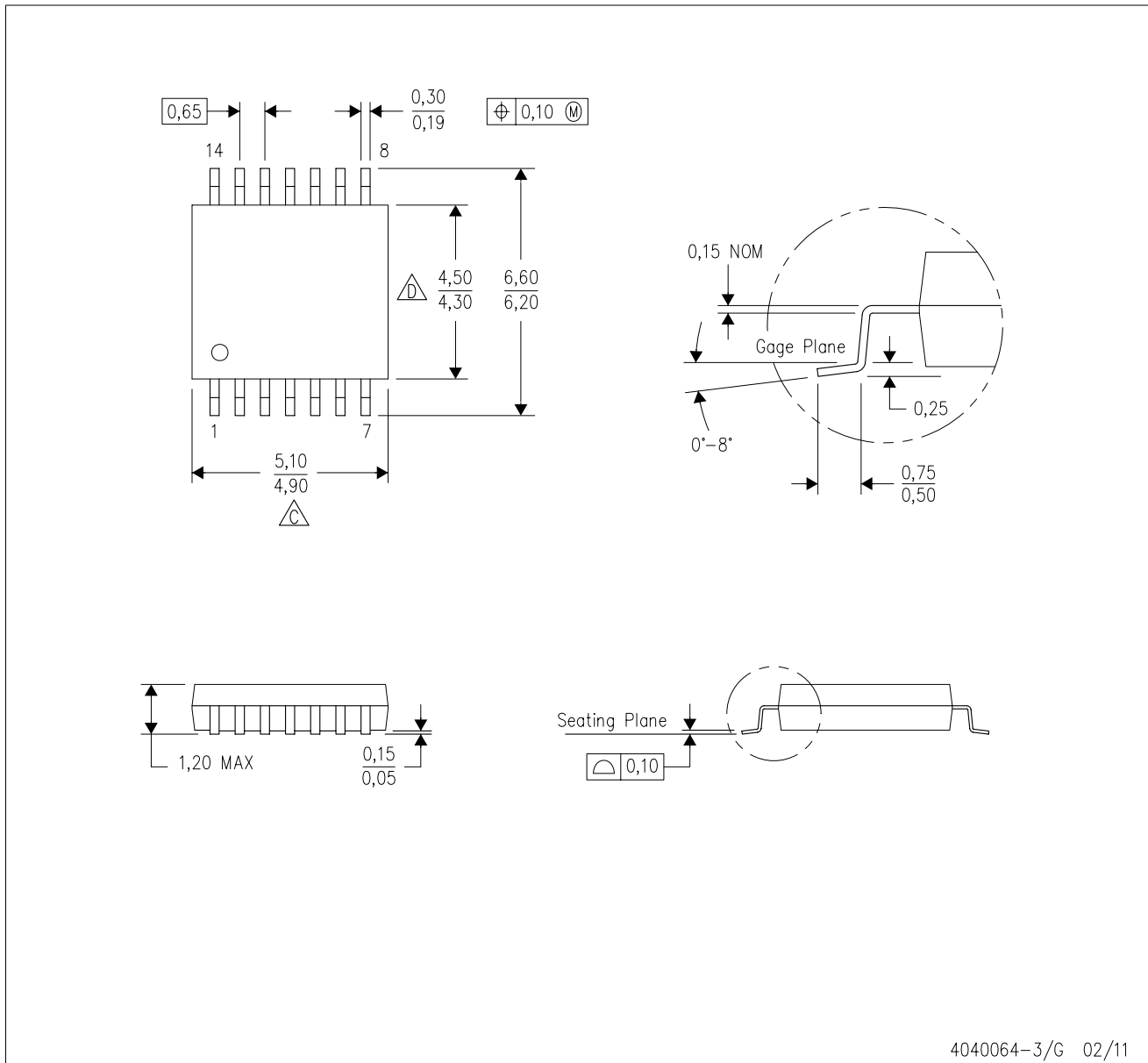
PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE

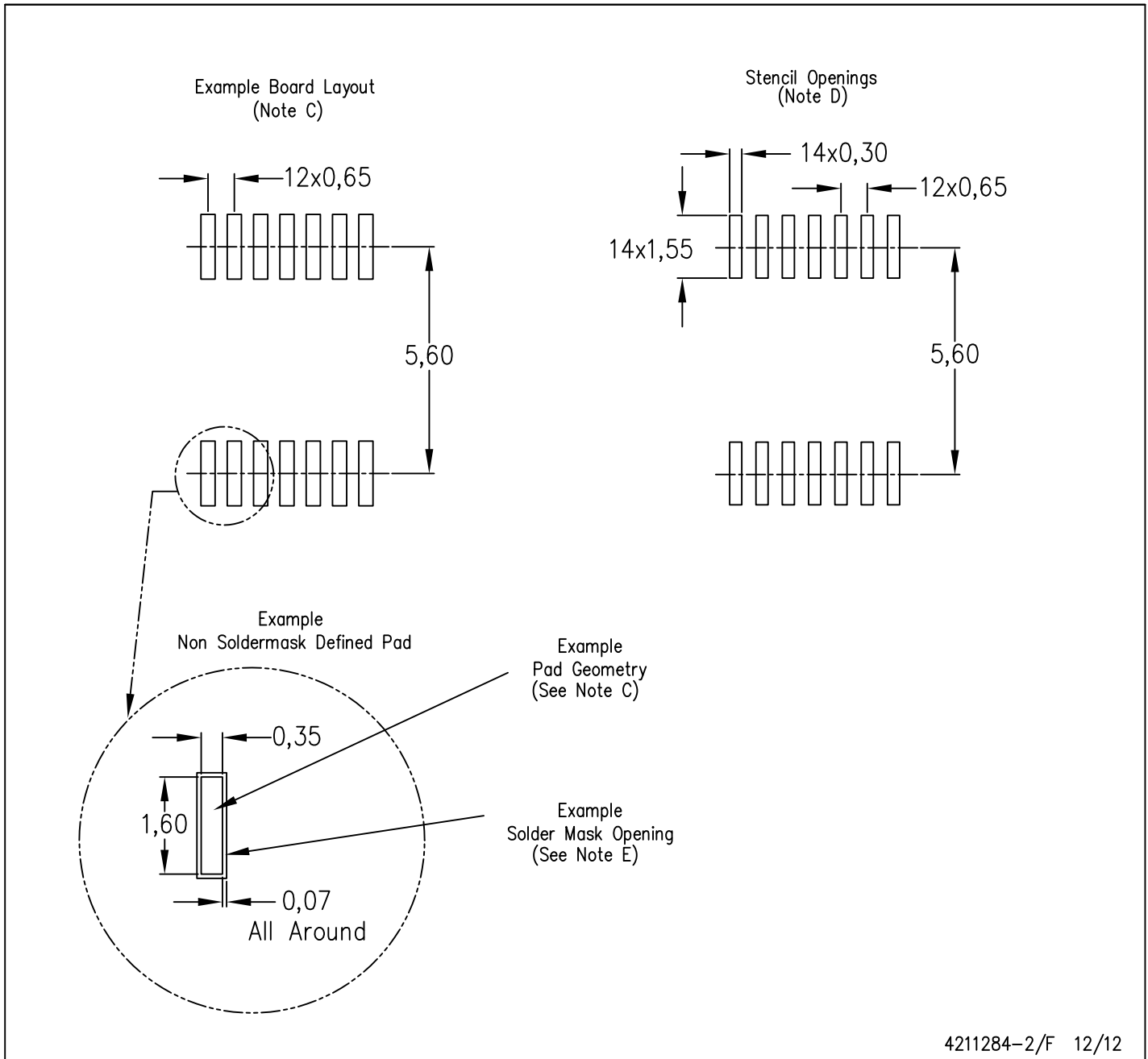


4040064-3/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4211284-2/F 12/12

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

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